



Welcome to [E-XFL.COM](https://www.e-xfl.com)

Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	19811
Number of Logic Elements/Cells	420000
Total RAM Bits	23625728
Number of I/O	704
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1517-BBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5agxfb5k4f40i5

Contents

Arria V GX, GT, SX, and ST Device Datasheet.....	1-1
Electrical Characteristics.....	1-1
Operating Conditions.....	1-1
Switching Characteristics.....	1-23
Transceiver Performance Specifications.....	1-23
Core Performance Specifications.....	1-43
Periphery Performance.....	1-49
HPS Specifications.....	1-58
Configuration Specifications.....	1-75
POR Specifications.....	1-75
FPGA JTAG Configuration Timing.....	1-76
FPP Configuration Timing.....	1-77
AS Configuration Timing.....	1-80
DCLK Frequency Specification in the AS Configuration Scheme.....	1-81
PS Configuration Timing.....	1-81
Initialization.....	1-83
Configuration Files.....	1-83
Minimum Configuration Time Estimation.....	1-84
Remote System Upgrades.....	1-86
User Watchdog Internal Oscillator Frequency Specifications.....	1-86
I/O Timing.....	1-86
Programmable IOE Delay.....	1-87
Programmable Output Buffer Delay.....	1-87
Glossary.....	1-88
Document Revision History.....	1-94
 Arria V GZ Device Datasheet.....	 2-1
Electrical Characteristics.....	2-1

Operating Conditions	2-1
Switching Characteristics	2-21
Transceiver Performance Specifications	2-21
Core Performance Specifications	2-37
Periphery Performance	2-44
Configuration Specification	2-56
POR Specifications	2-56
JTAG Configuration Specifications	2-57
Fast Passive Parallel (FPP) Configuration Timing	2-57
Active Serial Configuration Timing	2-65
Passive Serial Configuration Timing	2-67
Initialization	2-69
Configuration Files	2-69
Remote System Upgrades Circuitry Timing Specification	2-70
User Watchdog Internal Oscillator Frequency Specification	2-71
I/O Timing	2-71
Programmable IOE Delay	2-72
Programmable Output Buffer Delay	2-72
Glossary	2-73
Document Revision History	2-78

Symbol	Description	Minimum	Maximum	Unit
V _{CCPLL_HPS}	HPS PLL analog power supply	–0.50	3.25	V
V _{CC_AUX_SHARED}	HPS auxiliary power supply	–0.50	3.25	V
I _{OUT}	DC output current per pin	–25	40	mA
T _J	Operating junction temperature	–55	125	°C
T _{STG}	Storage temperature (no bias)	–65	150	°C

Maximum Allowed Overshoot and Undershoot Voltage

During transitions, input signals may overshoot to the voltage listed in the following table and undershoot to –2.0 V for input currents less than 100 mA and periods shorter than 20 ns.

The maximum allowed overshoot duration is specified as a percentage of high time over the lifetime of the device. A DC signal is equivalent to 100% duty cycle.

For example, a signal that overshoots to 4.00 V can only be at 4.00 V for ~15% over the lifetime of the device; for a device lifetime of 10 years, this amounts to 1.5 years.

Table 1-2: Maximum Allowed Overshoot During Transitions for Arria V Devices

This table lists the maximum allowed input overshoot voltage and the duration of the overshoot voltage as a percentage of device lifetime.

Symbol	Description	Condition (V)	Overshoot Duration as % of High Time	Unit
Vi (AC)	AC input voltage	3.8	100	%
		3.85	68	%
		3.9	45	%
		3.95	28	%
		4	15	%
		4.05	13	%
		4.1	11	%
		4.15	9	%
		4.2	8	%
		4.25	7	%
		4.3	5.4	%
		4.35	3.2	%
		4.4	1.9	%
		4.45	1.1	%
		4.5	0.6	%
		4.55	0.4	%
		4.6	0.2	%

Recommended Operating Conditions

This section lists the functional operation limits for the AC and DC parameters for Arria V devices.

Recommended Operating Conditions

Table 1-3: Recommended Operating Conditions for Arria V Devices

This table lists the steady-state voltage values expected from Arria V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Symbol	Description	Minimum ⁽⁵⁾	Typical	Maximum ⁽⁵⁾	Unit
V _{CCL_GXBL}	GX and SX speed grades—clock network power (left side)	1.08/1.12	1.1/1.15 ⁽⁶⁾	1.14/1.18	V
V _{CCL_GXBR}	GX and SX speed grades—clock network power (right side)				
V _{CCL_GXBL}	GT and ST speed grades—clock network power (left side)	1.17	1.20	1.23	V
V _{CCL_GXBR}	GT and ST speed grades—clock network power (right side)				

Related Information**Arria V GT, GX, ST, and SX Device Family Pin Connection Guidelines**

Provides more information about the power supply connection for different data rates.

HPS Power Supply Operating Conditions**Table 1-5: HPS Power Supply Operating Conditions for Arria V SX and ST Devices**

This table lists the steady-state voltage and current values expected from Arria V system-on-a-chip (SoC) devices with ARM®-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus. Refer to Recommended Operating Conditions for Arria V Devices table for the steady-state voltage values expected from the FPGA portion of the Arria V SoC devices.

Symbol	Description	Condition	Minimum ⁽⁷⁾	Typical	Maximum ⁽⁷⁾	Unit
V _{CC_HPS}	HPS core voltage and periphery circuitry power supply	–C4, –I5, –C5, –C6	1.07	1.1	1.13	V
		–I3	1.12	1.15	1.18	V

⁽⁵⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁷⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Symbol	Description	Condition	Minimum ⁽⁷⁾	Typical	Maximum ⁽⁷⁾	Unit
$V_{CCPD_HPS}^{(8)}$	HPS I/O pre-driver power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
V_{CCIO_HPS}	HPS I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V ⁽⁹⁾	1.283	1.35	1.418	V
$V_{CCRSTCLK_HPS}$	HPS reset and clock input pins power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
V_{CCPLL_HPS}	HPS PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V

⁽⁷⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

⁽⁸⁾ V_{CCPD_HPS} must be 2.5 V when V_{CCIO_HPS} is 2.5, 1.8, 1.5, or 1.2 V. V_{CCPD_HPS} must be 3.0 V when V_{CCIO_HPS} is 3.0 V. V_{CCPD_HPS} must be 3.3 V when V_{CCIO_HPS} is 3.3 V.

⁽⁹⁾ V_{CCIO_HPS} 1.35 V is supported for HPS row I/O bank only.

Symbol	Description	Condition	Minimum ⁽⁷⁾	Typical	Maximum ⁽⁷⁾	Unit
V _{CC_AUX_SHARED}	HPS auxiliary power supply	—	2.375	2.5	2.625	V

Related Information

Recommended Operating Conditions on page 1-4

Provides the steady-state voltage values for the FPGA portion of the device.

DC Characteristics**Supply Current and Power Consumption**

Altera offers two ways to estimate power for your design—the Excel-based Early Power Estimator (EPE) and the Quartus® Prime PowerPlay Power Analyzer feature.

Use the Excel-based EPE before you start your design to estimate the supply current for your design. The EPE provides a magnitude estimate of the device power because these currents vary greatly with the resources you use.

The Quartus Prime PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

Related Information

- **PowerPlay Early Power Estimator User Guide**
Provides more information about power estimation tools.
- **PowerPlay Power Analysis chapter, Quartus Prime Handbook**
Provides more information about power estimation tools.

⁽⁷⁾ The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

Parameter	Symbol	Condition	V _{CCIO} (V)												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold trip point	V _{TRIP}	—	0.3	0.9	0.375	1.125	0.68	1.07	0.7	1.7	0.8	2	0.8	2	V

OCT Calibration Accuracy Specifications

If you enable on-chip termination (OCT) calibration, calibration is automatically performed at power up for I/Os connected to the calibration block.

Table 1-8: OCT Calibration Accuracy Specifications for Arria V Devices

Calibration accuracy for the calibrated on-chip series termination (R_S OCT) and on-chip parallel termination (R_T OCT) are applicable at the moment of calibration. When process, voltage, and temperature (PVT) conditions change after calibration, the tolerance may change.

Symbol	Description	Condition (V)	Calibration Accuracy			Unit
			-I3, -C4	-I5, -C5	-C6	
25- Ω R_S	Internal series termination with calibration (25- Ω setting)	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2$	± 15	± 15	± 15	%
50- Ω R_S	Internal series termination with calibration (50- Ω setting)	$V_{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2$	± 15	± 15	± 15	%
34- Ω and 40- Ω R_S	Internal series termination with calibration (34- Ω and 40- Ω setting)	$V_{CCIO} = 1.5, 1.35, 1.25, 1.2$	± 15	± 15	± 15	%
48- Ω , 60- Ω , and 80- Ω R_S	Internal series termination with calibration (48- Ω , 60- Ω , and 80- Ω setting)	$V_{CCIO} = 1.2$	± 15	± 15	± 15	%
50- Ω R_T	Internal parallel termination with calibration (50- Ω setting)	$V_{CCIO} = 2.5, 1.8, 1.5, 1.2$	-10 to +40	-10 to +40	-10 to +40	%
20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω R_T	Internal parallel termination with calibration (20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω setting)	$V_{CCIO} = 1.5, 1.35, 1.25$	-10 to +40	-10 to +40	-10 to +40	%

Symbol	Description	V _{CCIO} (V)	Value	Unit
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/ ^o C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.35	0.200	
		1.25	0.200	
		1.2	0.317	

Pin Capacitance

Table 1-11: Pin Capacitance for Arria V Devices

Symbol	Description	Maximum	Unit
C _{IOTB}	Input capacitance on top/bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on left/right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output/feedback pins	6	pF
C _{IOVREF}	Input capacitance on V _{REF} pins	48	pF

Hot Socketing

Table 1-12: Hot Socketing Specifications for Arria V Devices

Symbol	Description	Maximum	Unit
I _{IOPIN} (DC)	DC current per I/O pin	300	μA
I _{IOPIN} (AC)	AC current per I/O pin	8 ⁽¹⁰⁾	mA
I _{XCVR-TX} (DC)	DC current per transceiver transmitter (TX) pin	100	mA

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
Data rate (10-Gbps transceiver) ⁽⁴⁴⁾	—	0.611	—	10.3125	Gbps
Absolute V_{MAX} for a receiver pin ⁽⁴⁵⁾	—	—	—	1.2	V
Absolute V_{MIN} for a receiver pin	—	-0.4	—	—	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) before device configuration	—	—	—	1.6	V
Maximum peak-to-peak differential input voltage V_{ID} (diff p-p) after device configuration	—	—	—	2.2	V
Minimum differential eye opening at the receiver serial input pins ⁽⁴⁶⁾	—	100	—	—	mV
V_{ICM} (AC coupled)	—	—	750 ⁽⁴⁷⁾ /800	—	mV
V_{ICM} (DC coupled)	$\leq 3.2\text{Gbps}$ ⁽⁴⁸⁾	670	700	730	mV
Differential on-chip termination resistors	85- Ω setting	85			Ω
	100- Ω setting	100			Ω
	120- Ω setting	120			Ω
	150- Ω setting	150			Ω
t_{LTR} ⁽⁴⁹⁾	—	—	—	10	μs
t_{LTD} ⁽⁵⁰⁾	—	4	—	—	μs

⁽⁴⁵⁾ The device cannot tolerate prolonged operation at this absolute maximum.

⁽⁴⁶⁾ The differential eye opening specification at the receiver input pins assumes that you have disabled the **Receiver Equalization** feature. If you enable the **Receiver Equalization** feature, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

⁽⁴⁷⁾ The AC coupled V_{ICM} is 750 mV for PCIe mode only.

⁽⁴⁸⁾ For standard protocol compliance, use AC coupling.

⁽⁴⁹⁾ t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

⁽⁵⁰⁾ t_{LTD} is time required for the receiver CDR to start recovering valid data after the `rx_is_lockedto data` signal goes high.

Typical TX V_{OD} Setting for Arria V Transceiver Channels with termination of 100 Ω Table 1-32: Typical TX V_{OD} Setting for Arria V Transceiver Channels with termination of 100 Ω

Symbol	V_{OD} Setting ⁽⁵⁸⁾	V_{OD} Value (mV)	V_{OD} Setting ⁽⁵⁸⁾	V_{OD} Value (mV)
V_{OD} differential peak-to-peak typical	6 ⁽⁵⁹⁾	120	34	680
	7 ⁽⁵⁹⁾	140	35	700
	8 ⁽⁵⁹⁾	160	36	720
	9	180	37	740
	10	200	38	760
	11	220	39	780
	12	240	40	800
	13	260	41	820
	14	280	42	840
	15	300	43	860
	16	320	44	880
	17	340	45	900
	18	360	46	920
	19	380	47	940
	20	400	48	960
	21	420	49	980
	22	440	50	1000
	23	460	51	1020
	24	480	52	1040

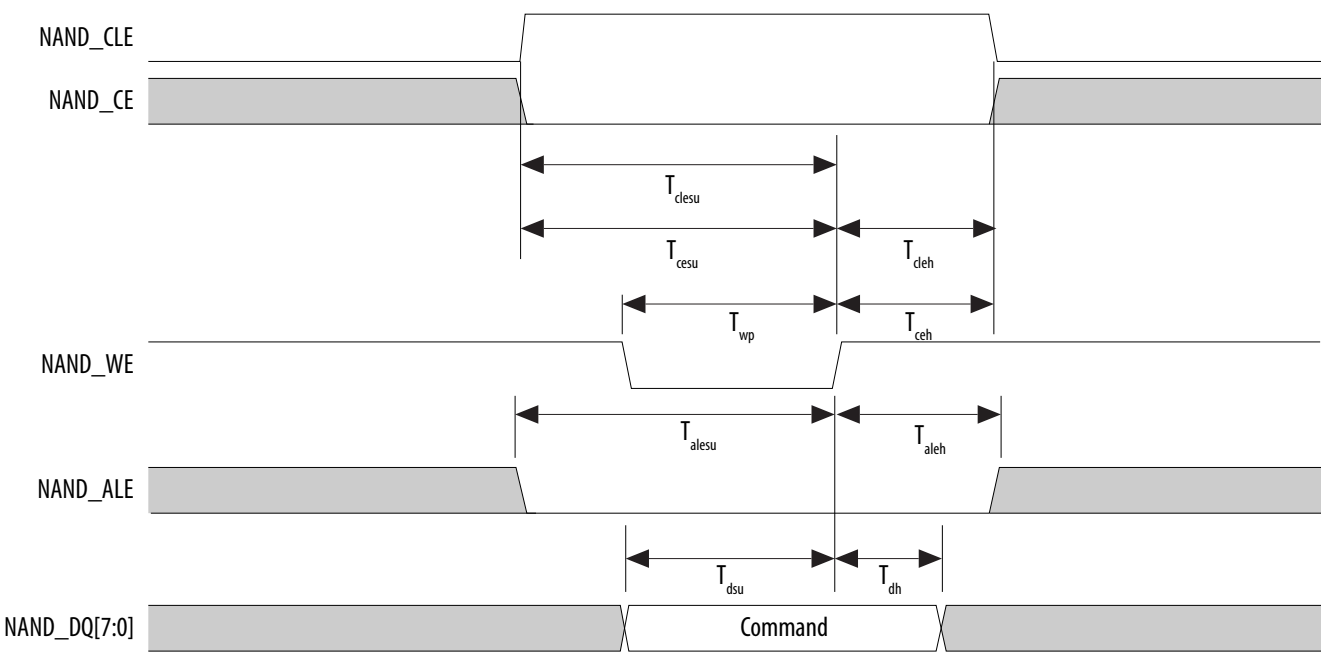
⁽⁵⁸⁾ Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.⁽⁵⁹⁾ Only valid for data rates ≤ 5 Gbps.

Table 1-34: Transceiver Compliance Specification for All Supported Protocol for Arria V GX, GT, SX, and ST Devices

Protocol	Sub-protocol	Data Rate (Mbps)
PCIe	PCIe Gen1	2,500
	PCIe Gen2	5,000
	PCIe Cable	2,500
XAUI	XAUI 2135	3,125
Serial RapidIO® (SRIO)	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
	SRIO 3125 LR	3,125
	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
	SRIO_6250_SR	6,250
	SRIO_6250_MR	6,250
	SRIO_6250_LR	6,250

Symbol	Description	Min	Max	Unit
$T_{dh}^{(89)}$	Data to write enable hold time	5	—	ns
T_{cea}	Chip enable to data access time	—	25	ns
T_{rea}	Read enable to data access time	—	16	ns
T_{rhz}	Read enable to data high impedance	—	100	ns
T_{rr}	Ready to read enable low	20	—	ns

Figure 1-17: NAND Command Latch Timing Diagram



Remote System Upgrades

Table 1-74: Remote System Upgrade Circuitry Timing Specifications for Arria V Devices

Parameter	Minimum	Unit
$t_{RU_nCONFIG}^{(110)}$	250	ns
$t_{RU_nRSTIMER}^{(111)}$	250	ns

Related Information

- [Remote System Upgrade State Machine](#)
Provides more information about configuration reset (RU_CONFIG) signal.
- [User Watchdog Timer](#)
Provides more information about reset_timer (RU_nRSTIMER) signal.

User Watchdog Internal Oscillator Frequency Specifications

Table 1-75: User Watchdog Internal Oscillator Frequency Specifications for Arria V Devices

Parameter	Minimum	Typical	Maximum	Unit
User watchdog internal oscillator frequency	5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O timing and the Quartus Prime Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis.

⁽¹¹⁰⁾ This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification.

⁽¹¹¹⁾ This is equivalent to strobing the reset timer input of the ALTREMOTE_UPDATE IP core high for the minimum timing specification.

The Quartus Prime Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

Related Information

[Arria V I/O Timing Spreadsheet](#)

Provides the Arria V Excel-based I/O timing spreadsheet.

Programmable IOE Delay

Table 1-76: I/O element (IOE) Programmable Delay for Arria V Devices

Parameter ⁽¹¹²⁾	Available Settings	Minimum Offset ⁽¹¹³⁾	Fast Model		Slow Model					Unit
			Industrial	Commercial	–C4	–C5	–C6	–I3	–I5	
D1	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns
D3	8	0	1.763	1.795	2.999	3.496	3.571	3.031	3.643	ns
D4	32	0	0.508	0.518	0.869	1.063	1.063	1.063	1.057	ns
D5	32	0	0.508	0.517	0.870	1.063	1.063	0.872	1.057	ns

Programmable Output Buffer Delay

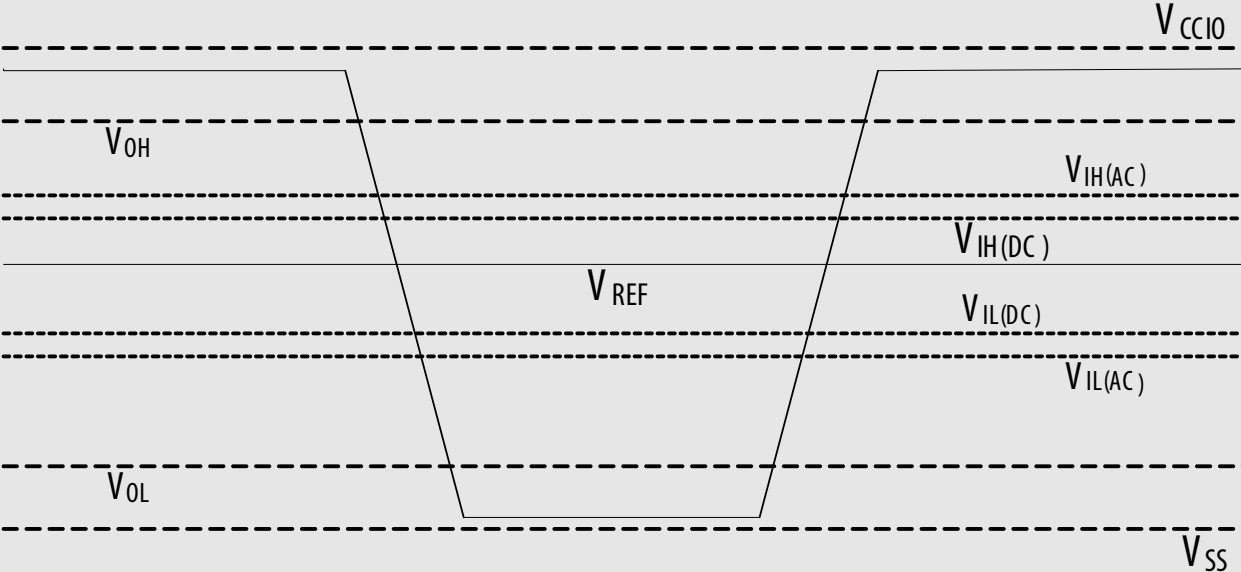
Table 1-77: Programmable Output Buffer Delay for Arria V Devices

This table lists the delay chain settings that control the rising and falling edge delays of the output buffer.

You can set the programmable output buffer delay in the Quartus Prime software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

⁽¹¹²⁾ You can set this value in the Quartus Prime software by selecting **D1**, **D3**, **D4**, and **D5** in the **Assignment Name** column of **Assignment Editor**.

⁽¹¹³⁾ Minimum offset does not include the intrinsic delay.

Term	Definition
Single-ended voltage referenced I/O standard	<p>The JEDEC standard for the SSTL and HSTL I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.</p> <p>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing.</p> <p>Single-Ended Voltage Referenced I/O Standard</p> 
t_C	High-speed receiver/transmitter input and output clock period.
TCCS (channel-to-channel-skew)	The timing difference between the fastest and slowest output edges, including the t_{CO} variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the Timing Diagram figure under SW in this table).
t_{DUTY}	High-speed I/O block—Duty cycle on high-speed transmitter output clock.

Date	Version	Changes
August 2013	3.5	<ul style="list-style-type: none">Removed “Pending silicon characterization” note in Table 29.Updated Table 25.
August 2013	3.4	<ul style="list-style-type: none">Removed Preliminary tags for Table 1, Table 2, Table 3, Table 4, Table 5, Table 6, Table 7, Table 9, Table 12, Table 13, Table 14, Table 15, Table 16, Table 17, Table 18, Table 19, Table 20, Table 21, Table 22, Table 23, Table 24, Table 25, Table 26, Table 27, Table 28, Table 29, Table 30, Table 31, Table 35, Table 36, Table 51, Table 53, Table 54, Table 55, Table 56, Table 57, Table 60, Table 62, and Table 64.Updated Table 1, Table 3, Table 11, Table 19, Table 20, Table 21, Table 22, Table 25, and Table 29.
June 2013	3.3	Updated Table 20, Table 21, Table 25, and Table 38.
May 2013	3.2	<ul style="list-style-type: none">Added Table 37.Updated Figure 8, Figure 9, Figure 20, Figure 22, and Figure 23.Updated Table 1, Table 5, Table 10, Table 13, Table 19, Table 20, Table 21, Table 23, Table 29, Table 39, Table 40, Table 46, Table 56, Table 57, Table 60, and Table 64.Updated industrial junction temperature range for –I3 speed grade in “PLL Specifications” section.
March 2013	3.1	<ul style="list-style-type: none">Added HPS reset information in the “HPS Specifications” section.Added Table 60.Updated Table 1, Table 3, Table 17, Table 20, Table 29, and Table 59.Updated Figure 21.

I/O Standard	V_{CCIO} (V) ⁽¹²⁸⁾			V_{ID} (mV) ⁽¹²⁹⁾			$V_{ICM(DC)}$ (V)			V_{OD} (V) ⁽¹³⁰⁾			V_{OCM} (V) ⁽¹³⁰⁾		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
RSDS (HIO) ⁽¹³³⁾	2.375	2.5	2.625	100	$V_{CM} = 1.25$ V	—	0.3	—	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO) ⁽¹³⁴⁾	2.375	2.5	2.625	200	—	600	0.4	—	1.325	0.25	—	0.6	1	1.2	1.4
LVPECL ^{(135), (136)}	—	—	—	300	—	—	0.6	$D_{MAX} \leq 700$ Mbps	1.8	—	—	—	—	—	—
	—	—	—	300	—	—	1	$D_{MAX} > 700$ Mbps	1.6	—	—	—	—	—	—

Related Information[Glossary](#) on page 2-73⁽¹²⁸⁾ Differential inputs are powered by VCCPD which requires 2.5 V.⁽¹²⁹⁾ The minimum VID value is applicable over the entire common mode range, VCM.⁽¹³⁰⁾ RL range: $90 \leq RL \leq 110 \Omega$.⁽¹³³⁾ For optimized RSBS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.⁽¹³⁴⁾ For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.⁽¹³⁵⁾ LVPECL is only supported on dedicated clock input pins.⁽¹³⁶⁾ For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.

Symbol	Conditions	C3, I3L			C4, I4			Unit
		Min	Typ	Max	Min	Typ	Max	
True Differential I/O Standards - f_{HSDR} (data rate)	SERDES factor $J = 3$ to 10 (182), (183)	(184)	—	1250	(184)	—	1050	Mbps
	SERDES factor $J \geq 4$ LVDS TX with DPA (185), (186), (187), (188)	(184)	—	1600	(184)	—	1250	Mbps
	SERDES factor $J = 2$, uses DDR Registers	(184)	—	(189)	(184)	—	(189)	Mbps
	SERDES factor $J = 1$, uses SDR Register	(184)	—	(189)	(184)	—	(189)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f_{HSDR} (data rate) (190)	SERDES factor $J = 4$ to 10 (191)	(184)	—	840	(184)	—	840	Mbps

(182) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.

(183) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design dependent and requires timing analysis.

(184) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.

(185) Arria V GZ RX LVDS will need DPA. For Arria V GZ TX LVDS, the receiver side component must have DPA.

(186) Requires package skew compensation with PCB trace length.

(187) Do not mix single-ended I/O buffer within LVDS I/O bank.

(188) Chip-to-chip communication only with a maximum load of 5 pF.

(189) The maximum ideal data rate is the SERDES factor (J) x the PLL maximum output frequency (f_{OUT}) provided you can close the design timing and the signal integrity simulation is clean.

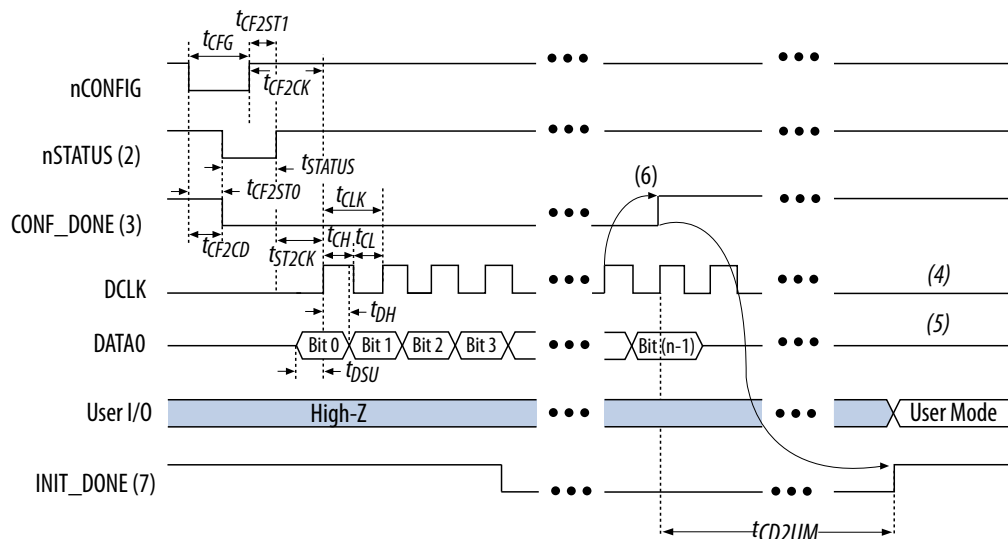
(190) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.

(191) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

Passive Serial Configuration Timing

Figure 2-10: PS Configuration Timing Waveform

Timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.



Notes:

1. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
2. After power-up, the Arria V GZ device holds nSTATUS low for the time of the POR delay.
3. After power-up, before and during configuration, CONF_DONE is low.
4. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
5. DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the Device and Pins Option.
6. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF_DONE is released high after the Arria V GZ device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
7. After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.